Electra House, 32 Southtown Road Great Yarmouth, Norfolk NR31 0DU, England Telephone +44 (0)1493 602602 Email:sales@midasdisplays.com www.midasdisplays.com

MDT0177AIS-MULTI	240 x 320	x 320 Multi Interface TFT N				
(MCT0177A0W240320PMLIPS)	Specification				
Version: 1		Date: 13/03/2017				
	Revision					
1 1	3/03/2017	First issue				

Display F			
Display Size	1.77"		
Resolution	240 x 320		
Orientation	Portrait		
Appearance	RGB		
Logic Voltage	3.3V		LIC
Interface	M <mark>ul</mark> ti		oHS mpliant
Brightness	450 c <mark>d/m²</mark>	/ V 30	mpliant
Touchscreen		00	mpnant
Module Size	34.7 x 46.70 x 2 <mark>.6</mark> 5mm		
Operating Temperature	-20°C ~ +70°C		
Pinout	45 way FFC	Box Quantity	Weight / Display
Pitch	m = n + f = 0.5mm	e sunr) \/

* - For full design functionality, please use this specification in conjunction with the ST7789S specification.(Provided Separately)

Display Accessories					
Part Number	Description				

Optional Variants					
Appearances	Voltage				

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silico n TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 1.77'TFT-LCD contains 240x320 pixels, and can display up to 65K colors.

* Features

-Low Input Voltage: VCC:3.3V(TYP);IOVCC:2.8-3.3V

-Display Colors of TFT LCD: 65K colors

-Interface: 8/9/16/18Bit MCU;

3/4SPI+16/18Bit RGB

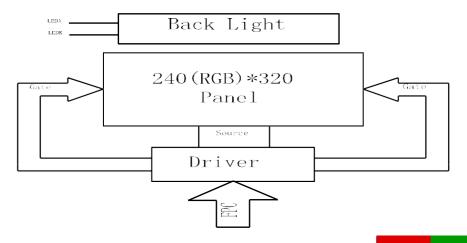
3-line/4-line Serial Interface

3-IIIIe/4-IIIIe Geliai IIIIeriace							
General Information	Specification	Unit	Note				
Items	Main Panel	Oilit					
Display area(AA)	26.64(H)*35.52(V) (1.77inch)	mm	-				
Driver element	TFT active matrix	-	-				
Display colors	65/262K	colors	-				
Number of pixels	240(RGB)*320	dots	-				
Pixel arrangement	RGB vertical stripe	-	-				
Pixel pitch	0.111(H)*0.111(V)	mm	-				
Viewing angle	Free	o'clock	-				
Controller IC	ST7789S	-	-				
Display mode	Transmissive/Normally black		-				
Operating temperature	-20~+70	$^{\circ}\mathbb{C}$	-				
Storage temperature	-30~+80	$^{\circ}\!\mathbb{C}$	-				

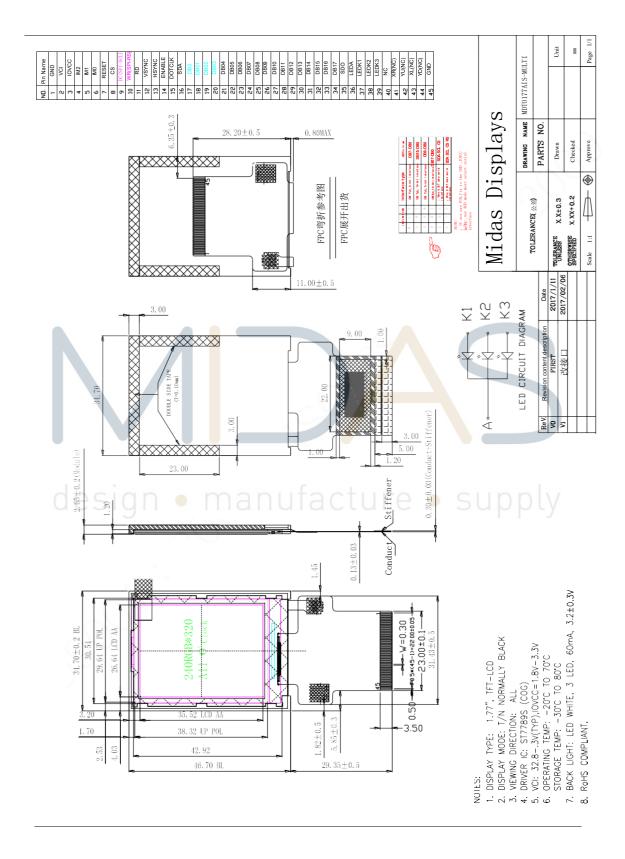
* Mechanical Information

Item		Min.	Тур.	Max.	Unit	Note
Module	Horizontal(H)		34.7		mm	-
size	Vertical(V)		46.7		mm	-
	Depth(D)		2.65		mm	-

Block Diagram



Outline dimension



Input terminal Pin Assignment

NO	OV/MDO!	DICCDIPTION	1/0
NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	Р
2	VCI/VCC	Supply voltage(3.3V).	
3	IOVCC	Supply voltage(1.65-3.3V).	Р
4	IM2		
5	IM1	Interface selecting signal.	I
6	IM0		I
7	RESET	This signal will reset the device and must be applied to properly initialize the chip.	I
8	cs	Chip select input pin ("Low" enable). fix this pin at VCI or GND when not in use.	I
9	DC(SPI-SCL)	-Display data/command selection pin in parallel interfaceThis pin is used to be serial interface clock. DC='1': display data or parameter. DC='0': command dataIf not used, please fix this pin at VDDI or DGND.	1
10	WR(SPI-RS)	 -Write enable in MCU parallel interface. - Display data/command selection pin in 4-line serial interface. - Second Data lane in 2 data lane serial interface. -If not used, please fix this pin at VDDI or DGND. 	I
11	RD	Serves as a read signal and MCU read data at the rising edge. fix this pin at VCI or GND when not in use.	I
12	VSYNC	Frame synchronous signal. Low active. Connect to I GND when DPI is not selected.	ı
13	HSYNC	Line synchronous signal. Low active. Connect to GND when DPI is not selected.	I
14	ENABLE	Data enable signal in DPI operation. Low: Select (Accessible) High: Not select (Inaccessible) Connect to GND when DPI is not selected.	I

1	<u></u>		<u> </u>
15	DOTCL K	Pixel clock signal. The data input timing is set on the rising edge. Connect to GND when DPI is not selected.	I
16	SDA	Serial data input/output pin in DBI Type C operation.	I
17~3 4	DB0~DB1 7	Data bus. Connect to GND when is not used.	Р
35	SDO	This pin is enabled when SDOE=1 and DBI Type C is used. With this setting, SDA can be used as an input pin and SDO pin can be used as an output pin without bidirectional bus to exe cute serial communication. If not used please open.	0
36	LED A	Anode pin of backlight.	
37	LEDK 1	Cathode pin of backlight.	Р
38	LEDK 2	Cathode pin of backlight.	Р
39	LEDK 3	Cathode pin of backlight.	Р
40	NC	NC	
41	XR(NC	Touch panel Right Glass Terminal	A/D
42	YU(NC Touch panel Top Film Terminal		A/D
43	XL(NC Touch panel LIFT Glass Terminal		A/D
44	YD(NC Touch panel Bottom Film Terminal		A/D
45	GND	Ground	Р

LCD Optical Characteristics

1 Optical specification

Item	Item Symbol		Condition	Min.	Тур.	Max.	Unit.	Note
Contrast Ratio		CR	Θ=0	500	600			
Response	Rising	T_R	Normal viewing		20	45		
time	Falling	T _F	angle	1	35	50	msec	
Color gan	nut	S(%)			49.3		%	
		Wx		0.260	0.300	0.340		
	White	W_{Y}		0.280	0.320	0.360		
	Red	R _X		0.609	0.629	0.649		
Color Filter		R _Y		0.307	0.327	0.347		
Chromacicity	Green	Gx		0.292	0.312	0.332		
		G _Y		0.535	0.555	0.575		
	Blue	B _X		0.144	0.164	0.184		
		By		0.149	0.169	0.189		
		Θι		60	85			
	Hor.	ΘR		60	85			
Viewing angle		Θυ	CR>10	60	85			
	Ver.	ΘD		60	85			
Option View D	irection	D 6	manufa	+ Free	0 61	innly	/	
manutacture supply								

2 Measuring Condition

■ Measuring surrounding: dark room

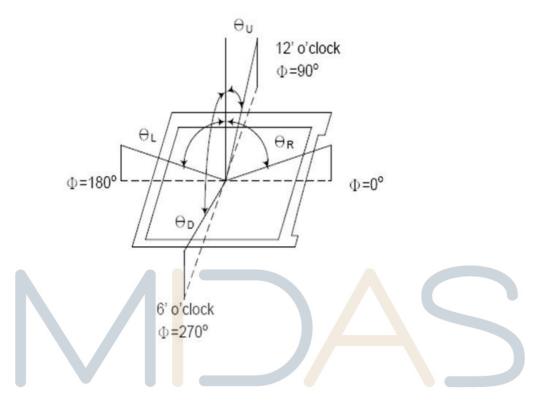
■ Ambient temperature: 25±2°C

■ 15min. warm-up time.

3 Measuring Equipment

■ FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

Note (1) Definition of Viewing Angle:



Note (2) Definition of Contrast Ratio (CR):

measured at the center point of panel

Luminance with all pixels white

CR = ____

Luminance with all pixels black

Electrical Characteristics

1 Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VDD	-0.3	4.6	V
Digital interface supple Voltage	VDDIO	-0.3	4.6	V
Operating temperature	T _{OP}	-20	+70	$^{\circ}$
Storage temperature	T _{ST}	-30	+80	$^{\circ}$

NOTE: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

2 DC Electrical Characteristics

					LV	
Characteristics	Symbol	Min.	Тур.	Max.	Unit	Note
Digital Supply Voltage	VDD	2.4	2.8	3.3	V	
Digital interface supple Voltage	VDDIO	1.65	1.8	3.3	V	
Normal mode Current consumption	IDD		7		mA	
	Vih	0.7VDDIO		VDDIO	V	
Level input voltage	VIL	GND		0.3VDDIO	V	
	Vон	0.8VDDIO		VDDIO	V	
Level output voltage	Vol	GND		0.2VDDIO	V	

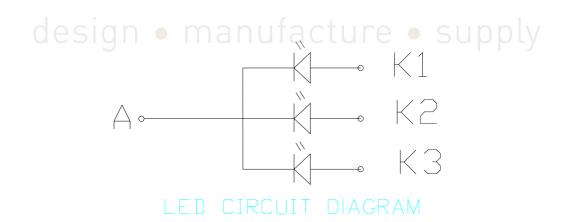
3 LED Backlight Characteristics

The back-light system is edge-lighting type with 3 chips White LED

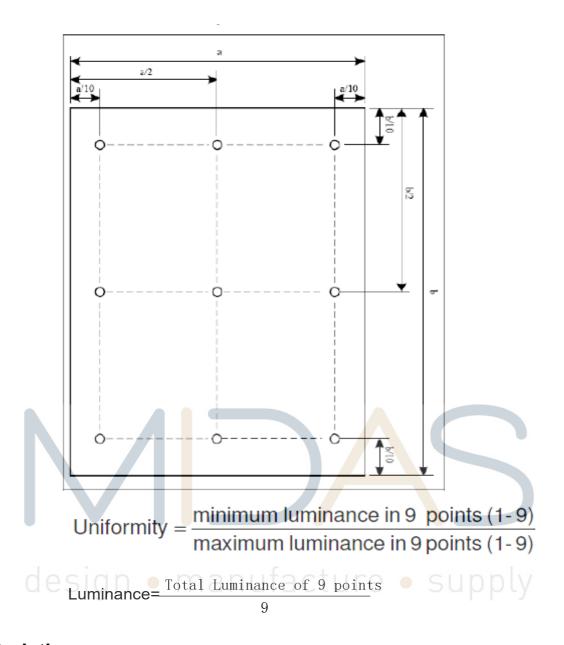
Item	Symbol	Min.	Тур.	Max.	Unit	Note
Forward Current	lF	45	60		mA	
Forward Voltage	VF		3.2		V	
LCM Luminance	Lv	400	450		cd/m2	Note3
LED life time	Hr	50000			Hour	Note1,2
Uniformity	AVg	80			%	Note3

Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition:

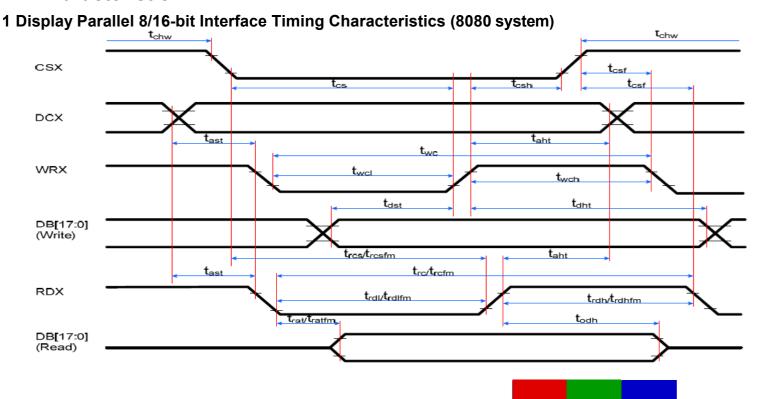
Ta=25±3 °C, typical IL value indicated in the above table until the brightness becomes less than 50%. Note (2) File "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25°C and IL=60mA. The LED lifetime could be decreased if operating IL is larger than 60mA. The constant current driving method is suggested.



NOTE 3: Luminance Uniformity of these 9 points is defined as below:

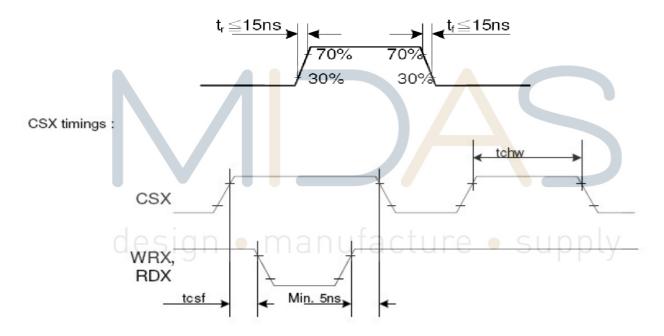


AC Characteristic



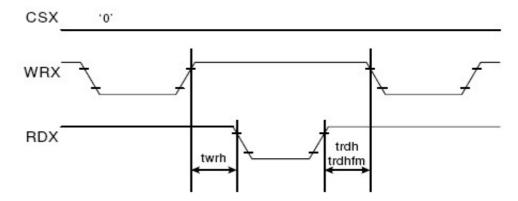
Signal	Symbol	Parameter	min	max	Unit	Description
DCX tast Address setup time		Address setup time	0	-	ns	
DCX taht		Address hold time (Write/Read)	10	-	ns	
tchw		CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
CSX	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
	twc	Write cycle	66	-	ns	
WRX	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
	trcfm	Read Cycle (FM)	450	-	ns	
RDX (FM)	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
	trc	Read cycle (ID)	160	-	ns	
RDX (ID)	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[47.0]	tdst	Write data setup time	10	-	ns	
D[17:0],	tdht	Write data hold time	10	-	ns	For maximum CL 20nF
D[15:0], D[8:0],	trat	Read access time	-	40	ns	For maximum CL=30pF For minimum CL=8pF
D[8.0], D[7:0]	tratfm	Read access time	-	340	ns	TOT IIIIIIIIIIIIII OL=OPE
ال ال	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 °C, IOVCC=1.65V to 2.8V, VCI=2.6V to 3.3V, GND=0V



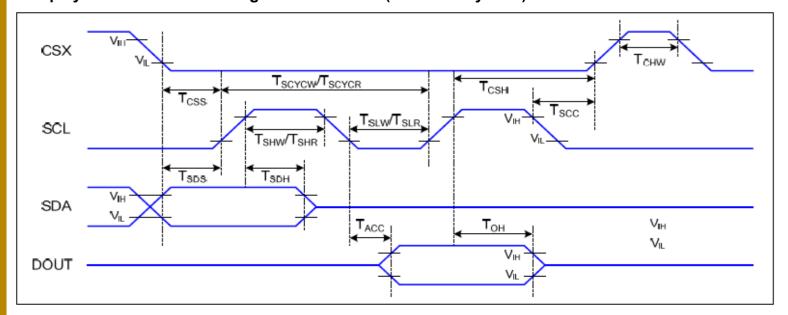
Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

Write to read or read to write timings:



Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

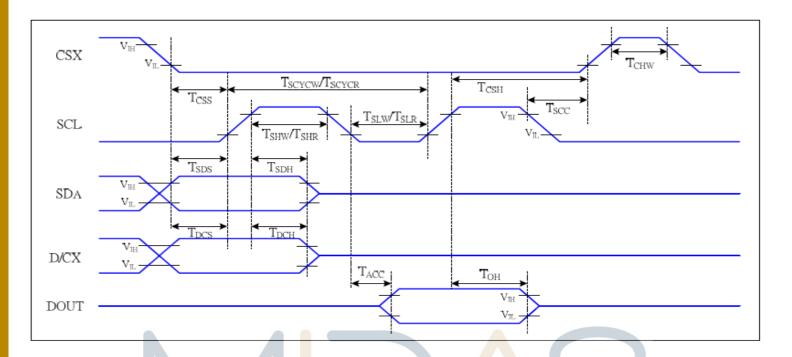
2 Display Serial Interface Timing Characteristics (3-line SPI system)



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 $^{\circ}\mathrm{C}$

Signal	Symbol	/mbol Parameter I		Max	Unit	Description
T _{css} Chip select setup time (write)		15		ns		
	T _{CSH}	Chip select <mark>ho</mark> ld time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{scc}	Chip select <mark>ho</mark> ld time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	nnly
	Tshw	SCL "H" pulse width (Write)	15	E	ns	opty
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
DO01	T _{OH} Output disable time		15	50	ns	For minimum CL=8pF

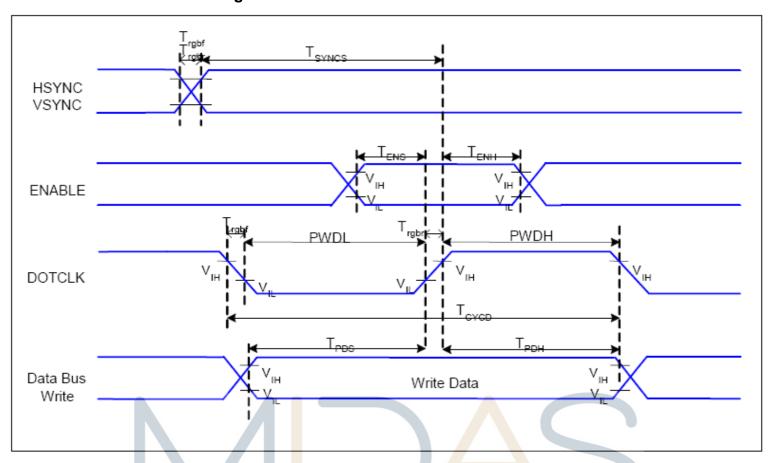
3 Display Serial Interface Timing Characteristics (4-line SPI system)



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 $^{\circ}$ C

Signal	Symbol	Para <mark>m</mark> eter	MIN	MAX	Unit	Description
	T _{css}	Chip select se <mark>tu</mark> p time (write)	15		ns	
T _{CSH}		Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	nnlv
	T _{CHW}	Chip select "H" pulse width	40		ns	
T _{SCYCW}		Serial clock cycle (Write)	66		ns	-write command & data
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	ram
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	Talli
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	-read command & data
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	ram
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	Talli
D/CX	T _{DCS}	D/CX setup time	10		ns	
D/CX	T _{DCH}	D/CX hold time	10		ns	
SDA	T_{SDS}	T _{SDS} Data setup time			ns	
(DIN)	T _{SDH}	Data hold time			ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
D001	Тон	Output disable time	15	50	ns	For minimum CL=8pF

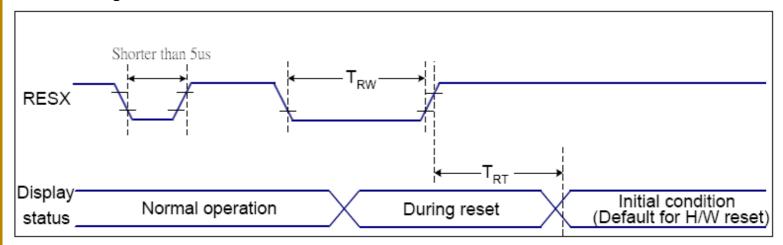
4 Parallel RGB Interface Timing Characteristics



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 ℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	O E S I (T _{SYNCS}	VSYNC, HSYNC Setup Time		51	ns	ty
ENABLE	T _{ENS} Enable Setup Time		25	-	ns	
ENABLE	T _{ENH} Enable Hold Time		25	-	ns	
	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
DOTCLK	PWDL DOTCLK Low-level Pulse Width		60	-	ns	
DOTCLK	T _{CYCD} DOTCLK Cycle Time		120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB T _{PDS}		PD Data Setup Time	50	-	ns	
DB	T _{PDH}	PD Data Hold Time	50	-	ns	

5 Reset Timing Characteristics



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 ℃

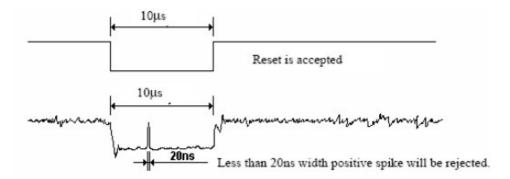
Related Pins	Symbol Parameter		MIN	MAX	Unit
	TRW	Reset pulse duration	10	-	us
RESX	TDT	TRT Reset cancel		5 (Note 1, 5)	ms
	IKI			120 (Note 1, 6, 7)	ms

Notes:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
 - 2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action		
Shorter than 5us	Reset Rejected		
Longer than 9us	Reset		
Between 5us and 9us	Reset starts		

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.
 - 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

LCD Module Out-Going Quality Level

1 VISUAL & FUNCTION INSPECTION STANDARD

1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

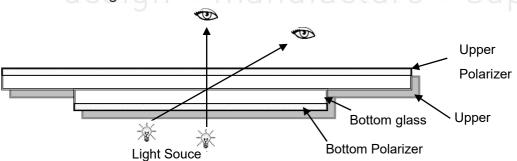
Temperature : 25±5°C

Humidity: 65%±10%RH

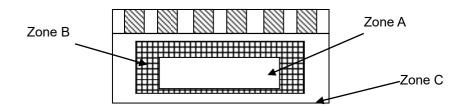
Viewing Angle: Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



1.2 Definition



Zone A: Effective Viewing Area(Character or Digit can be seen)

Zone B: Viewing Area except Zone A

Zone <u>C</u>: Outside (Zone A+Zone B) which can not be seen after assembly by <u>customer</u>.)

Note:

As a general <u>rule _visual</u> defects in Zone C can be ignored when it doesn't <u>effect</u> product function or appearance after assembly by <u>customer</u>.

1.3 Sampling Plan

According to GB/T 2828-2003; normal inspection, Class II

AQL:

M <mark>a</mark> jor <u>defect</u>	Minor defect	
0.65	1.5	

LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be	Criteria	Classification of
	inspected	manufacture • sui	defects
	9	1) No display, Open or miss line	
1	Functional defects	2) Display abnormally, Short	
'	Fullctional defects	3) Backlight no lighting, abnormal lighting.	
		4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing	
3	Oddine dimension	is not allowed	
4	Color tone	Color unevenness, refer to limited sample	
5	Soldering	Good <u>soldering</u> . Peeling off is not allowed.	Minor
5	appearance		IVIII IOI
6	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

1.4 Criteria (Visual)

Number Items			Criteria(mm)			
1.0 LCD Crack/Broken	(1) The edge of LCD broken					
NOTE:			Х	Υ	Z	
X: Length Y: Width			≤3.0mm	<pre><inner border="" line="" of="" pre="" seal<="" the=""></inner></pre>	≤T	
Z: Height L: Length of ITO, T: Height of LCD	(2)LCD corner broken esign • manufa (3) LCD crack	act	x ≤3.0r	YZ		

Number	Items		Crit	eria (mm)	Criteria (mm)					
2.0	Spot defect	① light dot(LCD dent, stain	/TP/Polarizer bl	ack/white	spot , l	ight d	ot, pinhole,			
		Zone	Accep able Qty			zy –				
\\		Size (mm)	А	В		С				
-		Ф≤0.10	 Ignor	re						
	·	0.10<Φ≤0.20	3(distance	 ≧ 10mm)						
	X	0.20<Φ≤0.25	2	<u> </u>		lgnor				
		Ф>0.25	0							
	Φ=(X+Y)/2	②Dim spot(LCD	/TP/Polarizer dir	m dot, ligh	nt leaka	ge、c	l lark spot)			
		Zone		cceptable		<u>-</u>				
		Size (mm)	А	В		С				
		Ф≤0.1	Ignor	re						
		0.10<Φ≤0.20	3(distance ≩			lanor				
		0.20<Φ≤0.30	2			Ignore	2			
		Ф>0. <mark>30</mark>	0							
		③ Polarizer accidented spot								
		Zone Acceptable Qt								
		Size (mm)	A	В		С				
		Ф≤0.2	Ignore							
	daci	0.3<Φ≤0.5	2(distance ≥ 10mm)			Ignor	e			
	ucsi	Ф>0.5	muracione sup				ry			
	Line defect			Acc	ceptable					
	(LCD/TP	CD/TP Width(mm)		Α	<u>'</u> В	C	;			
	/Polarizer black/white	Ф≤0.03	Igno e	Igno	re					
	line, scratch,	0.03 <w≤0.05< td=""><td>L≤3.0</td><td>N≤</td><td></td><td>Igno</td><td>ore</td></w≤0.05<>	L≤3.0	N≤		Igno	ore			
	stain)	0.05 <w≤0.08< td=""><td>L≤2.0</td><td>N≤</td><td>2</td><td>-</td><td></td></w≤0.08<>	L≤2.0	N≤	2	-				
		0.08 <w< td=""><td>Defi</td><td>ine as spot</td><td>defect</td><td></td><td></td></w<>	Defi	ine as spot	defect					
			Acce	eptable Qty	,					
	Polarizer	Zone Size (mm)	Α	В	С					
3.0	Bubble	Φ≤0.2	l Ignore							
		0.2<Φ≤0.4	3(distance≧10	≧ 10 m)						
		0.4<Φ≤0.6	2		Ignore					
		0.6<Ф	0							
4.0	SMT	According to IPC-A- part are major defec				defect	and missing			

	Size Φ(mm)	A	cceptable C	Qty
	Size Φ(IIIII)	Α	В	С
TP bubble/	Ф≤0.1	lgn	ore	
	0.1<Φ≤0.25	3 (dist	ance≧	Ignoro
accidented	0.25<Φ≤0.3	2		Ignore
spot	0.3<Ф	0		
Assembly deflection	beyond the edge of backlight ≤0.15mm			



design • manufacture • supply

5.0 TP Related			1規律性
	Newton Ring	Newton Ring area>1/3 TP area NG Newton Ring area≤1/3 TP area OK	2.排泉津生
			似牛顿环
	TP corner broken X: length Y: width Z: height	X Y Z Z <lcd *<="" td="" thicknes="" x≤3.0mm="" y≤3.0mm=""><td>Z</td></lcd>	Z
desig	TP edge broken X: length Y: width Z: height	Circuitry broken is not allowed. X Y Z Z <lcd *="" allowed.<="" broken="" circuitry="" is="" not="" td="" thicknes="" x≤6.0mm="" y≤2.0mm=""><td>Z</td></lcd>	Z

Criteria (functional items)

Number	Items	Criteria (mm)		
1	No display	Not allowed		
2	Missing segment	Not allowed		
3	Short	Not allowed		
4	Backlight no lighting	Not allowed		
5	TP no function	Not allowed		

Reliability Test Result

1 Condition

Item	Condition	Sample Size	Test Result	Note
Low Temperature	-20°C, 96HR	3ea	nass	
Operating Life test	-20 C, 901 IIX	Sea	pass	-
Thermal Humidity	70℃90%RH, 96HR	3ea	pass	
Operating Life test	70 C90 / (IXII, 901 IIX	Jea	разз	_
Temperature Cycle ON/OFF	-20°C ↔ 70°C, ON/OFF, 20CYC	3ea	pass	(1)
test	-20 € ↔ 70 €, ON/OFF, 20€16			
High Temperature	80℃, 96HR	200	nass	
Storage test		3ea	pass	-
Low Temperature	20% 06110	200		
Storage test	−30°C, 96HR	3ea	pass	-
ESD test	150pF, 330Ω , ±6KV(Contact)/± 8KV(Air), 5 points/panel,	3ea	naaa	
	10 times/point	sea	pass	
desi	The sample should be allowed to stand the	appty	/	
	following 5 cycles of operation: TSTL for 30 minutes ->			
Thermal Shock Resistance	normal temperature for 5 minutes -> TSTH for 30	3ea	pass	
	minutes -> normal temperature for 5 minutes, as one			
cycle, then taking it out and drying it at normal				
	temperature, and allowing it stand for 24 hours			
Box Drop Test	1 Corner 3 Edges 6 faces, 66cm(MEDIUM BOX)	1box	pass	-

Note (1) ON Time over 10 seconds, OFF Time under 10 seconds

Cautions and Handling Precautions

1 Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.

Do not warp or twist the module during assembly work.

- (2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- (4) Do not allow drops of water or chemicals to remain on the display surface.

If you have the droplets for a long time, staining and discoloration may occur.

- (5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- (6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.

Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.

- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static; it may cause damage to the CMOS ICs.
- (9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (10) Do not disassemble the module.
- (11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (12) Pins of I/F connector shall not be touched directly with bare hands.
- (13) Do not connect, disconnect the module in the "Power ON" condition.
- (14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence



2 Storage and Transportation.

- (1) Do not leave the panel in high temperature, and high humidity for a long time.
- (2) Do not store the TFT-LCD module in direct sunlight.
- (3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- (4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
- In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- (5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.